74AHC595Q
Automotive, 8-Bit Serial-In/Serial-Out or Parallel-Out Shift Register with 3-State Controlled Outputs

GENERAL DESCRIPTION

The 74AHC595Q is an 8-bit serial-in/serial-out or parallel-out shift register with 3-state controlled outputs designed for 2.0V to 5.5V V_{CC} operation.

The device integrates an 8-bit shift register and an 8-bit D-type storage register. The storage register features parallel 3-state outputs. The shift register provides a clear input ($\overline{SRCLR}$) with direct overriding function, a serial input (SER) and a serial output ($Q_{H'}$) to implement cascading. When output enable input ($\overline{OE}$) is held low, the data in storage register will appear at the outputs. When $\overline{OE}$ is held high, all outputs except $Q_{H'}$ are in high-impedance state.

Both the shift register and storage register have separate clocks. The shift register clock (SRCLK) and storage register clock (RCLK) are positive-edge triggered. If the SRCLK and RCLK are connected together, the shift register always leads one clock pulse than the storage register all the time.

The device is AEC-Q100 qualified (Automotive Electronics Council (AEC) standard Q100 Grade 1) and it is suitable for automotive applications.

The 74AHC595Q is available in Green TSSOP-16 and TQFN-2.5×3.5-16L packages. It operates over a temperature range of -40℃ to +125℃.

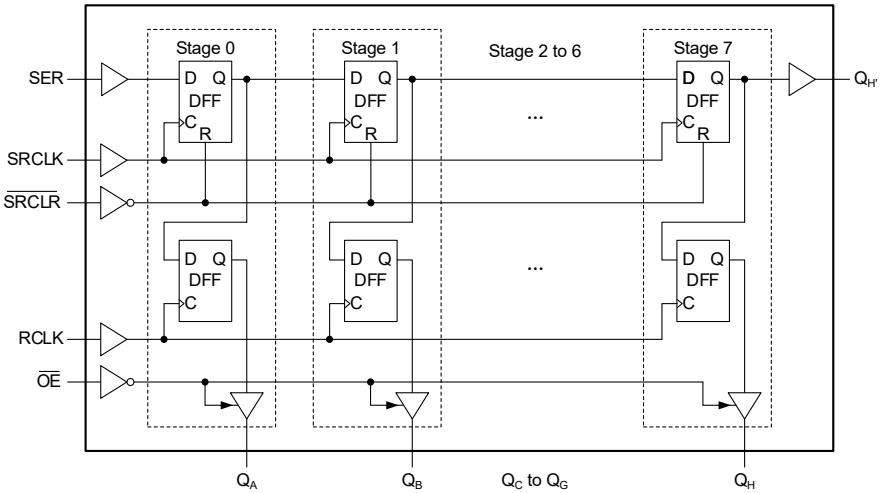
FEATURES

- **AEC-Q100 Qualified for Automotive Applications**
  Device Temperature Grade 1
  T_A = -40℃ to +125℃
- **Wide Supply Voltage Range: 2.0V to 5.5V**
- **8-Bit Serial-In/Serial-Out or Parallel-Out Shift Register**
- **Direct Clear Input of Shift Register**
- **-40℃ to +125℃ Operating Temperature Range**
- **Available in Green TSSOP-16 and TQFN-2.5×3.5-16L Packages**

APPLICATIONS

Automotive Applications
Medical Equipment

LOGIC DIAGRAM



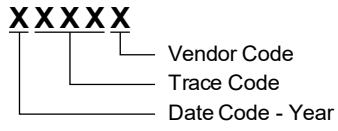
PACKAGE/ORDERING INFORMATION

MODEL	PACKAGE DESCRIPTION	SPECIFIED TEMPERATURE RANGE	ORDERING NUMBER	PACKAGE TOP MARKING	PACKING OPTION
74AHC595Q	TSSOP-16	-40℃ to +125℃	74AHC595QTS16G/TR	1DXTS16 XXXXX	Tape and Reel, 4000
	TQFN-2.5×3.5-16L	-40℃ to +125℃	74AHC595QTRG16G/TR	1DYTRG XXXXYY	Tape and Reel, 8000

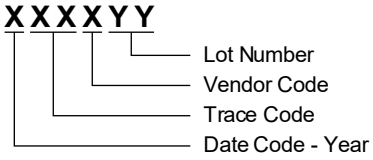
MARKING INFORMATION

NOTE: XXXXX = Date Code, Trace Code and Vendor Code. XXXX = Date Code, Trace Code and Vendor Code.

TSSOP-16



TQFN-2.5×3.5-16L



Green (RoHS & HSF): SG Micro Corp defines "Green" to mean Pb-Free (RoHS compatible) and free of halogen substances. If you have additional comments or questions, please contact your SGMICRO representative directly.

ABSOLUTE MAXIMUM RATINGS

Supply Voltage Range, V_{CC} ..... -0.5V to 7.0V
Input Voltage Range, V_I (1) ..... -0.5V to 7.0V
Output Voltage Range, V_O (1) -0.5V to MIN(7.0V, V_{CC} + 0.5V)
Input Clamp Current, I_{IK} (V_I < 0V) .....-20mA
Output Clamp Current, I_{OK} (V_O < 0V or V_O > V_{CC})..... ±20mA
Continuous Output Current, I_O (V_O = 0V to V_{CC}) ..... ±25mA
Continuous Current through V_{CC} or GND ..... ±75mA
Junction Temperature (2) .....+150℃
Storage Temperature Range .....-65℃ to +150℃
Lead Temperature (Soldering, 10s).....+260℃
ESD Susceptibility (3) (4)
HBM.....±5000V
CDM .....±1000V

NOTES:

1. The input and output voltage ratings may be exceeded if the input and output clamp current ratings are observed.

2. The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability.

3. For human body model (HBM), all pins comply with AEC-Q100-002 specification.

4. For charged device model (CDM), all pins comply with AEC-Q100-011 specification.

5. Unused input pins must be held at V_{CC} or GND to guarantee the device in normal operation.

RECOMMENDED OPERATING CONDITIONS

Supply Voltage Range, V_{CC}..... 2.0V to 5.5V
Input Voltage Range, V_I (5) ..... 0V to 5.5V
Output Voltage Range, V_O.....0V to V_{CC}
Input Transition Rise or Fall Rate, Δt/ΔV
V_{CC} = 3.3V ± 0.3V..... 100ns/V (MAX)
V_{CC} = 5.0V ± 0.5V..... 20ns/V (MAX)
Operating Temperature Range..... -40℃ to +125℃

OVERSTRESS CAUTION

Stresses beyond those listed in Absolute Maximum Ratings may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect reliability. Functional operation of the device at any conditions beyond those indicated in the Recommended Operating Conditions section is not implied.

ESD SENSITIVITY CAUTION

This integrated circuit can be damaged if ESD protections are not considered carefully. SGMICRO recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage. ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because even small parametric changes could cause the device not to meet the published specifications.

DISCLAIMER

SG Micro Corp reserves the right to make any change in circuit design, or specifications without prior notice.

FUNCTION TABLE

CONTROL INPUTS				INPUT	OUTPUTS		FUNCTION
SRCLK	RCLK	$\overline{OE}$	$\overline{SRCLR}$	SER	$Q_{H'}$	Q_A ~ Q_H	
X	*X*	L	L	*X*	L	NC	When $\overline{SRCLR}$ is low, it only affects the shift register.
X	↑	L	L	*X*	L	L	Load the empty shift register into the storage register.
X	*X*	H	L	*X*	L	Z	Shift register is reset and all parallel outputs are in high -impedance state.
↑	*X*	L	H	H	$Q_{G'}$	NC	When shift register stage 0 goes high, data of all shift register stages shifted through, e.g. the serial output ($Q_{H'}$) presents the previous state of stage 6 (internal $Q_{G'}$).
X	↑	L	H	*X*	NC	$Q_{x'}$	Data of shift register (internal $Q_{x'}$) is transferred to the storage register and parallel output stages.
↑	↑	L	H	*X*	$Q_{G'}$	$Q_{x'}$	Data of shift register shifted through, previous data of the shift register is transferred to the storage register and parallel output stages.

H = High Voltage Level

L = Low Voltage Level

↑ = Low-to-High Clock Transition

Z = High-Impedance State

NC = No Change

X = Don't Care

TIMING DIAGRAM

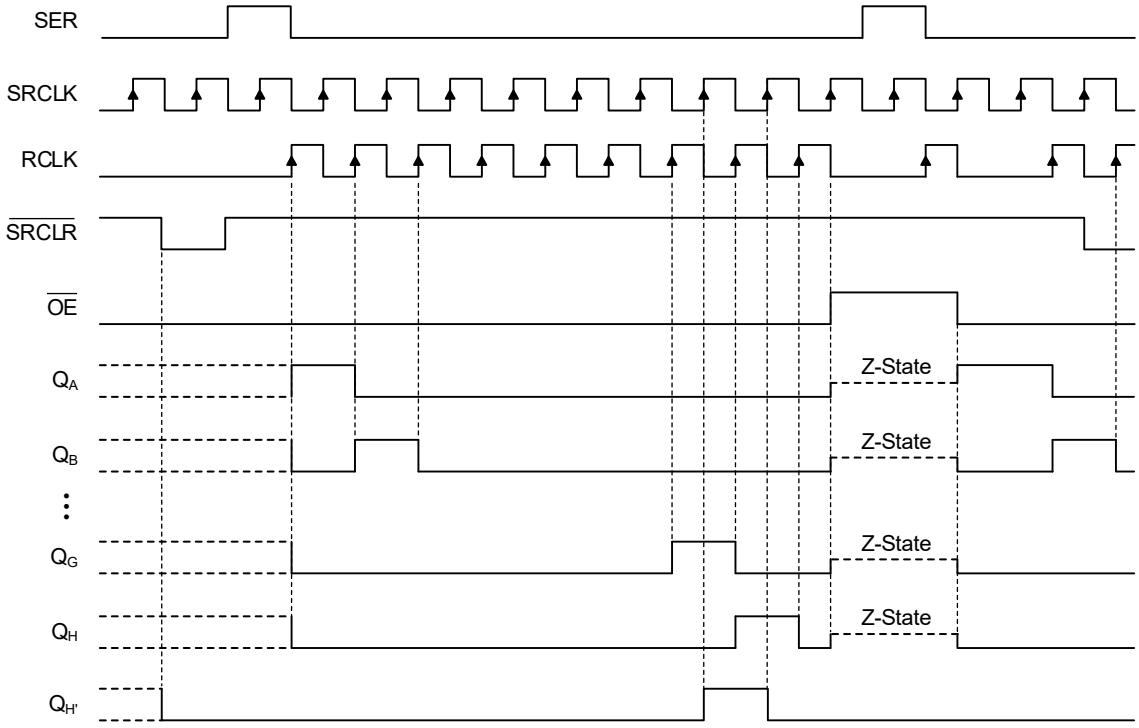
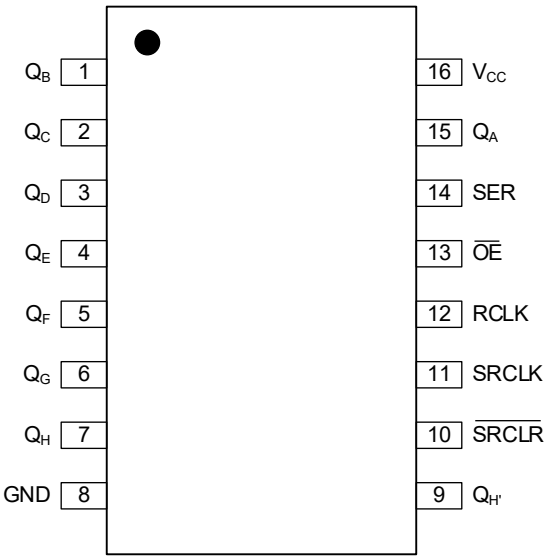


Figure 1. Timing Diagram

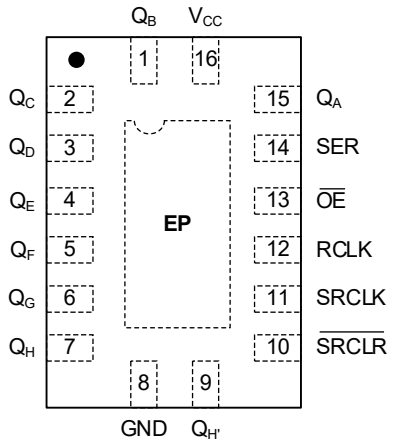
PIN CONFIGURATIONS

(TOP VIEW)



TSSOP-16

(TOP VIEW)



TQFN-2.5×3.5-16L

PIN DESCRIPTION

PIN	NAME	FUNCTION
15, 1, 2, 3, 4, 5, 6, 7	Q_A, Q_B, Q_C, Q_D, Q_E, Q_F, Q_G, Q_H	Parallel Data Outputs.
8	GND	Ground.
9	$Q_{H'}$	Serial Data Output.
10	$\overline{SRCLR}$	Shift Register Clear Input (Active-Low).
11	SRCLK	Shift Register Clock Input (Rising Edge Triggered).
12	RCLK	Storage Register Clock Input (Rising Edge Triggered).
13	$\overline{OE}$	Output Enable Input (Active-Low).
14	SER	Serial Data Input.
16	V_{CC}	Power Supply.
Exposed Pad	EP	Connect it to GND internally. This pad is not an electrical connection point. TQFN-2.5×3.5-16L package only.

ELECTRICAL CHARACTERISTICS

(Full = -40℃ to +125℃, all typical values are measured at T_A = +25℃, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	TEMP	MIN	TYP	MAX	UNITS
High-Level Input Voltage	V_{IH}	V_{CC} = 2.0V	Full	1.5			V
		V_{CC} = 3.0V	Full	2.1			
		V_{CC} = 5.5V	Full	3.85			
Low-Level Input Voltage	V_{IL}	V_{CC} = 2.0V	Full			0.5	V
		V_{CC} = 3.0V	Full			0.9	
		V_{CC} = 5.5V	Full			1.65	
High-Level Output Voltage	V_{OH}	V_{CC} = 2.0V, I_{OH} = -50μA	Full	1.9	1.995		V
		V_{CC} = 3.0V, I_{OH} = -50μA	Full	2.9	2.995		
		V_{CC} = 4.5V, I_{OH} = -50μA	Full	4.4	4.495		
		V_{CC} = 3.0V, I_{OH} = -4mA	Full	2.5	2.85		
		V_{CC} = 4.5V, I_{OH} = -8mA	Full	3.8	4.3		
Low-Level Output Voltage	V_{OL}	V_{CC} = 2.0V, I_{OL} = 50μA	Full		0.005	0.1	V
		V_{CC} = 3.0V, I_{OL} = 50μA	Full		0.005	0.1	
		V_{CC} = 4.5V, I_{OL} = 50μA	Full		0.005	0.1	
		V_{CC} = 3.0V, I_{OL} = 4mA	Full		0.15	0.5	
		V_{CC} = 4.5V, I_{OL} = 8mA	Full		0.20	0.5	
Input Leakage Current	I_I	V_{CC} = 0V to 5.5V, V_I = 5.5V or GND	Full		±0.01	±1	μA
Off-State Output Current	I_{OZ}	Q_A ~ Q_H, V_{CC} = 5.5V, V_I = V_{CC} or GND, V_O = V_{CC} or GND, $\overline{OE}$ = V_{IH} or V_{IL}	Full		±0.01	±5	μA
Supply Current	I_{CC}	V_{CC} = 5.5V, V_I = V_{CC} or GND, I_O = 0A	Full		0.02	5	μA
Input Capacitance	C_I	V_{CC} = 5.0V, V_I = V_{CC} or GND	+25℃		4		pF
Output Capacitance	C_O	V_{CC} = 5.0V, V_O = V_{CC} or GND	+25℃		5.5		pF

DYNAMIC CHARACTERISTICS

(See Figure 2 for test circuit. Full = -40℃ to +125℃, C_L = 50pF, all typical values are measured at T_A = +25℃, V_{CC} = 3.3V and 5.0V respectively, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS		TEMP	MIN (1)	TYP	MAX (1)	UNITS
Low-to-High Propagation Delay	t_{PLH}	RCLK to Q_A ~ Q_H, see Figure 4	V_{CC} = 3.3V ± 0.3V	Full	1	8.5	14.2	ns
			V_{CC} = 5.0V ± 0.5V	Full	0.5	6.5	10.2	
		SRCLK to $Q_{H'}$, see Figure 3	V_{CC} = 3.3V ± 0.3V	Full	1	9.0	14.4	
			V_{CC} = 5.0V ± 0.5V	Full	1	6.5	10.3	
High-to-Low Propagation Delay	t_{PHL}	RCLK to Q_A ~ Q_H, see Figure 4	V_{CC} = 3.3V ± 0.3V	Full	1	8.5	13.6	ns
			V_{CC} = 5.0V ± 0.5V	Full	1	6.5	10.2	
		SRCLK to $Q_{H'}$, see Figure 3	V_{CC} = 3.3V ± 0.3V	Full	1	8.5	13.9	
			V_{CC} = 5.0V ± 0.5V	Full	0.5	8.5	13.7	
		$\overline{SRCLR}$ to $Q_{H'}$, see Figure 6	V_{CC} = 3.3V ± 0.3V	Full	1	7.5	14.9	
			V_{CC} = 5.0V ± 0.5V	Full	0.5	6.5	11.7	
Off-to-High Propagation Delay	t_{PZH}	$\overline{OE}$ to Q_A ~ Q_H, see Figure 7	V_{CC} = 3.3V ± 0.3V	Full	1	7.5	13.0	ns
			V_{CC} = 5.0V ± 0.5V	Full	0.5	6.0	9.6	
Off-to-Low Propagation Delay	t_{PZL}		V_{CC} = 3.3V ± 0.3V	Full	1	7.5	12.0	
			V_{CC} = 5.0V ± 0.5V	Full	0.5	6.0	9.4	
High-to-Off Propagation Delay	t_{PHZ}	$\overline{OE}$ to Q_A ~ Q_H, see Figure 7	V_{CC} = 3.3V ± 0.3V	Full	1	11.0	15.8	ns
			V_{CC} = 5.0V ± 0.5V	Full	1	8.0	11.4	
Low-to-Off Propagation Delay	t_{PLZ}		V_{CC} = 3.3V ± 0.3V	Full	1	11.0	16.8	
			V_{CC} = 5.0V ± 0.5V	Full	1	6.5	12.2	
Maximum Frequency	f_{MAX}	See Figure 3 and Figure 4	V_{CC} = 3.3V ± 0.3V	Full	90	130		MHz
			V_{CC} = 5.0V ± 0.5V	Full	100	155		

NOTE:

1. Specified by design and characterization, not production tested.

DYNAMIC CHARACTERISTICS (continued)

(See Figure 2 for test circuit. Full = -40℃ to +125℃, C_L = 50pF, all typical values are measured at T_A = +25℃, V_{CC} = 3.3V and 5.0V respectively, unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS		TEMP	MIN (1)	TYP	MAX (1)	UNITS
Pulse Width	t_W	SRCLK high or low, see Figure 3	V_{CC} = 3.3V ± 0.3V	Full	6			ns
			V_{CC} = 5.0V ± 0.5V	Full	6			
		RCLK high or low, see Figure 4	V_{CC} = 3.3V ± 0.3V	Full	6			
			V_{CC} = 5.0V ± 0.5V	Full	6			
		$\overline{SRCLR}$ low, see Figure 6	V_{CC} = 3.3V ± 0.3V	Full	9			
			V_{CC} = 5.0V ± 0.5V	Full	9			
Setup Time	t_{SU}	SER before SRCLK ↑, see Figure 5	V_{CC} = 3.3V ± 0.3V	Full	4			ns
			V_{CC} = 5.0V ± 0.5V	Full	3			
		SRCLK ↑ before RCLK ↑ (2), see Figure 4	V_{CC} = 3.3V ± 0.3V	Full	7			
			V_{CC} = 5.0V ± 0.5V	Full	4			
		$\overline{SRCLR}$ low before RCLK ↑, see Figure 6	V_{CC} = 3.3V ± 0.3V	Full	7			
			V_{CC} = 5.0V ± 0.5V	Full	5			
		$\overline{SRCLR}$ high (inactive) before SRCLK ↑, see Figure 6	V_{CC} = 3.3V ± 0.3V	Full	2			
			V_{CC} = 5.0V ± 0.5V	Full	2			
Hold Time	t_H	SER after SRCLK ↑, see Figure 5	V_{CC} = 3.3V ± 0.3V	Full	2.5			ns
			V_{CC} = 5.0V ± 0.5V	Full	2			
Power Dissipation Capacitance (3) (4)	C_{PD}	No load, V_{CC} = 5.0V ± 0.5V, f = 10MHz		+25℃		85		pF

NOTES:

1. Specified by design and characterization, not production tested.

2. The setup time enables the storage register to get stable data from the shift register. In this case where clocks can be tied together, the shift register is a clock pulse in front of the storage register.

3. C_{PD} is used to determine the dynamic power dissipation (P_D in μW).

$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$

where:

f_i = Input frequency in MHz.

f_o = Output frequency in MHz.

C_L = Output load capacitance in pF.

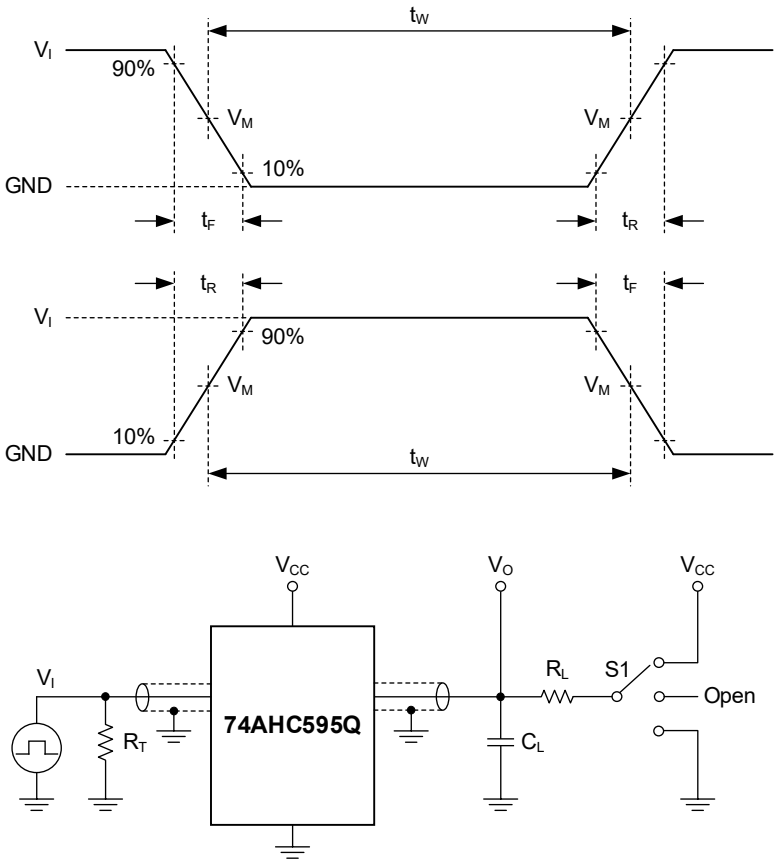
V_{CC} = Supply voltage in Volts.

N = Number of inputs switching.

$\Sigma(C_L \times V_{CC}^2 \times f_o)$ = Sum of outputs.

4. All 9 outputs switching.

TEST CIRCUIT



Test conditions are given in Table 1.

Definitions test circuit:

R_L: Load resistance.

C_L: Load capacitance (includes jig and probe).

R_T: Termination resistance (equals to output impedance Z_O of the pulse generator).

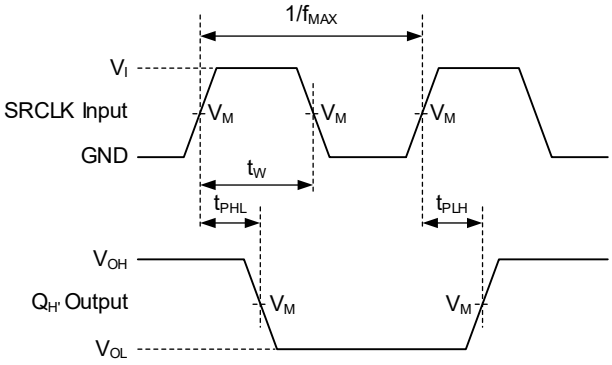
S1: Test selection switch.

Figure 2. Test Circuit for Measuring Switching Times

Table 1. Test Conditions

SUPPLY VOLTAGE	INPUT		LOAD		S1 POSITION		
V_{CC}	V_I	t_R, t_F	C_L	R_L	t_{PHL}, t_{PLH}	t_{PZH}, t_{PHZ}	t_{PZL}, t_{PLZ}
2.0V to 5.5V	V_{CC}	≤ 3.0ns	50pF	1kΩ	Open	GND	V_{CC}

WAVEFORMS

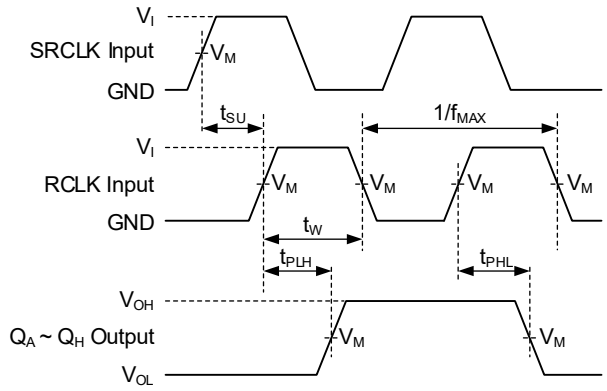


Test conditions are given in Table 1.

Measurement points are given in Table 2.

Logic levels: V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Figure 3. Shift Register Clock Input to Output Propagation Delay Times, Pulse Width and Maximum Frequency

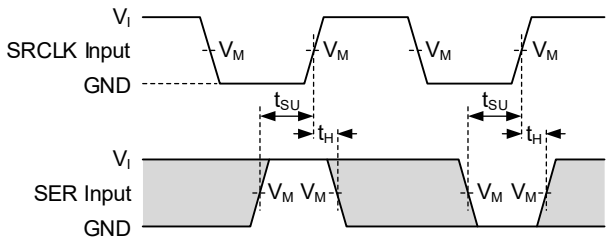


Test conditions are given in Table 1.

Measurement points are given in Table 2.

Logic levels: V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Figure 4. Storage Register Clock Input to Output Propagation Delay Times, Shift Register Clock to Storage Register Clock Setup Time, Pulse Width and Maximum Frequency



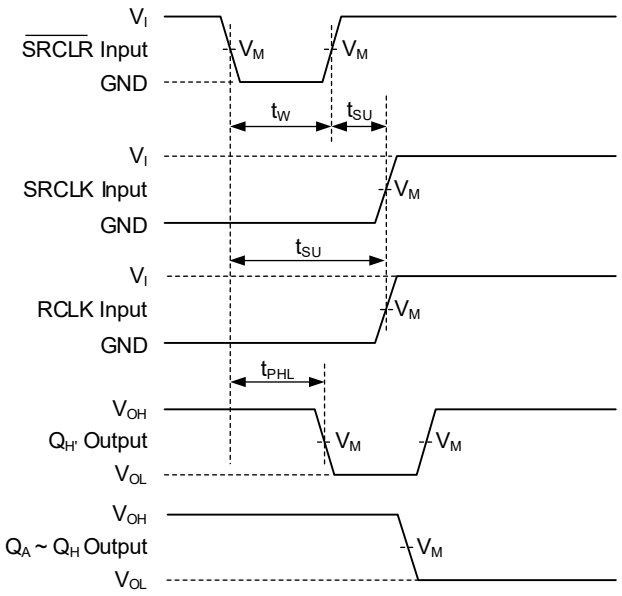
Test conditions are given in Table 1.

Measurement points are given in Table 2.

The shaded areas refer to when the input is allowed to change for predictable output performance.

Figure 5. Data Setup and Hold Times

WAVEFORMS (continued)

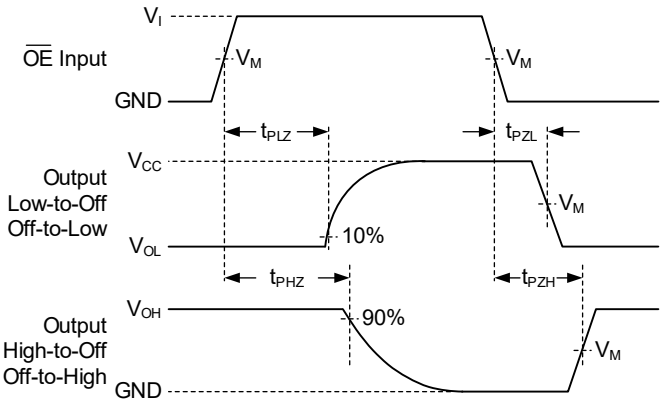


Test conditions are given in Table 1.

Measurement points are given in Table 2.

Logic levels: V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Figure 6. Clear Input to Output Propagation Delay Times, Pulse Width and Setup Time



Test conditions are given in Table 1.

Measurement points are given in Table 2.

Logic levels: V_{OL} and V_{OH} are typical output voltage levels that occur with the output load.

Figure 7. Enable and Disable Times

Table 2. Measurement Points

SUPPLY VOLTAGE	INPUT		OUTPUT
V_{CC}	V_I	V_M (1)	V_M
2.0V to 5.5V	V_{CC}	0.5 × V_{CC}	0.5 × V_{CC}

NOTE:

1. The measurement points should be V_{IH} or V_{IL} when the input rising or falling time exceeds 3.0ns.

REVISION HISTORY

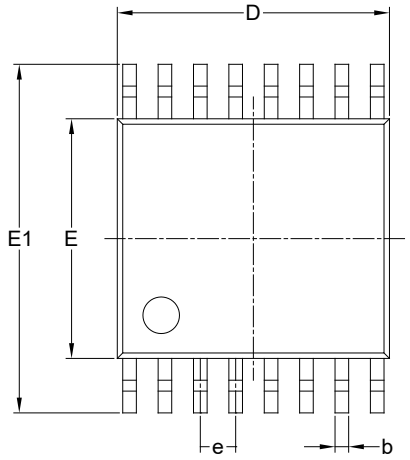
NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

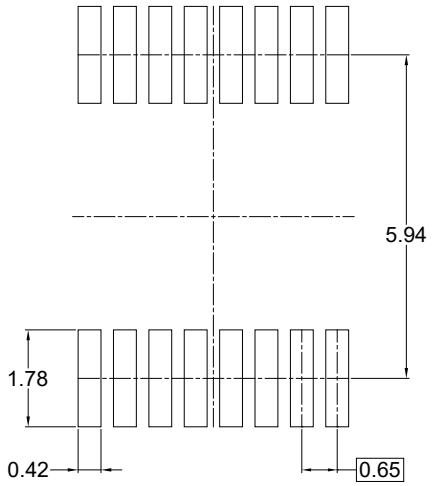
JUNE 2025 – REV.A to REV.A.1	Page
Updated Electrical Characteristics section	5
Added TQFN-2.5×3.5-16L package	All

Changes from Original (FEBRUARY 2025) to REV.A	Page
Changed from product preview to production data	All

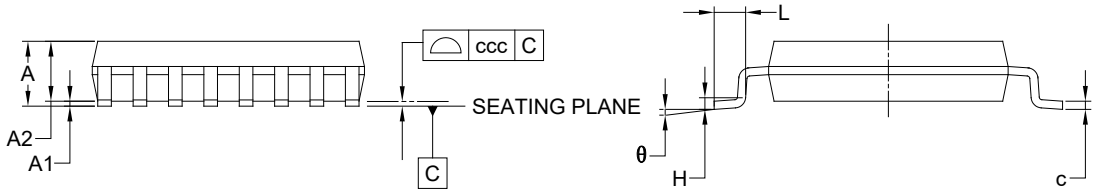
PACKAGE OUTLINE DIMENSIONS

TSSOP-16





RECOMMENDED LAND PATTERN (Unit: mm)

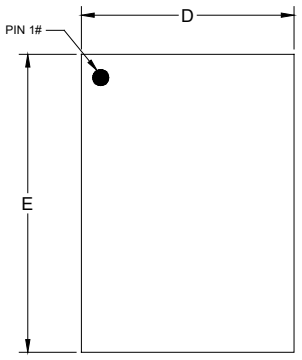


Symbol	Dimensions In Millimeters		
	MIN	NOM	MAX
A	-	-	1.200
A1	0.050	-	0.150
A2	0.800	-	1.050
b	0.190	-	0.300
c	0.090	-	0.200
D	4.860	-	5.100
E	4.300	-	4.500
E1	6.200	-	6.600
e	0.650 BSC		
L	0.450	-	0.750
H	0.250 TYP		
θ	0°	-	8°
ccc	0.100		

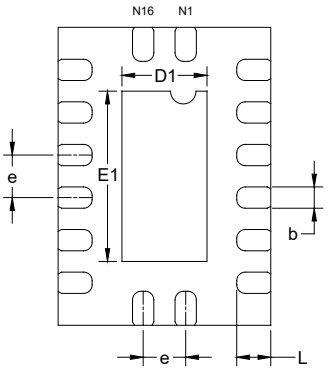
NOTES:
1. This drawing is subject to change without notice.
2. The dimensions do not include mold flashes, protrusions or gate burrs.
3. Reference JEDEC MO-153.

PACKAGE OUTLINE DIMENSIONS

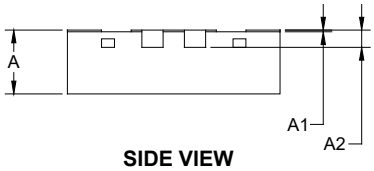
TQFN-2.5×3.5-16L



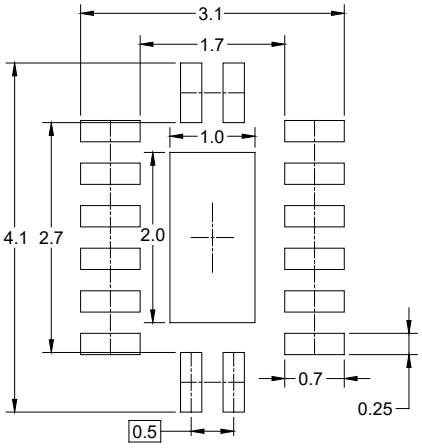
TOP VIEW



BOTTOM VIEW



SIDE VIEW



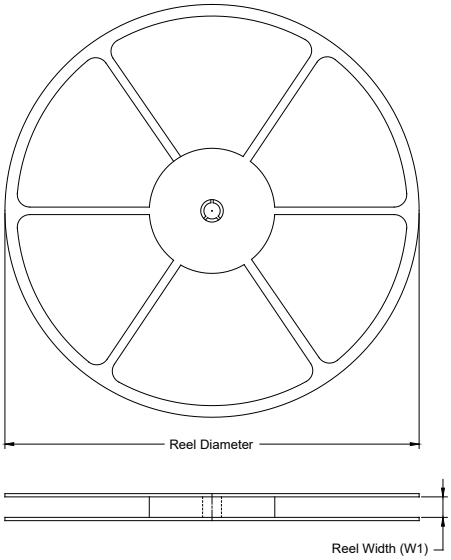
RECOMMENDED LAND PATTERN (Unit: mm)

Symbol	Dimensions In Millimeters		
	MIN	NOM	MAX
A	0.70	0.75	0.80
A1	0.00	0.02	0.05
A2		0.203 REF	
b	0.20	0.25	0.30
D	2.40	2.50	2.60
D1	0.85	1.00	1.15
E	3.40	3.50	3.60
E1	1.85	2.00	2.15
e	0.45	0.50	0.55
L	0.30	0.40	0.50

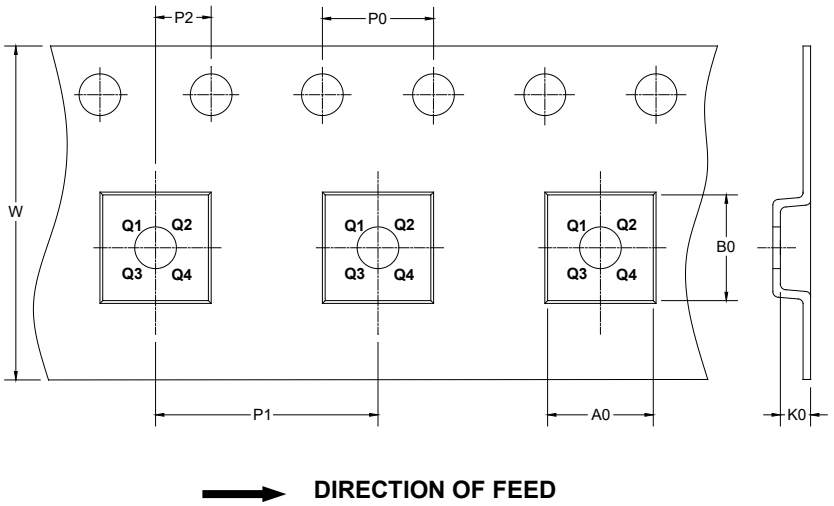
NOTE: This drawing is subject to change without notice.

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



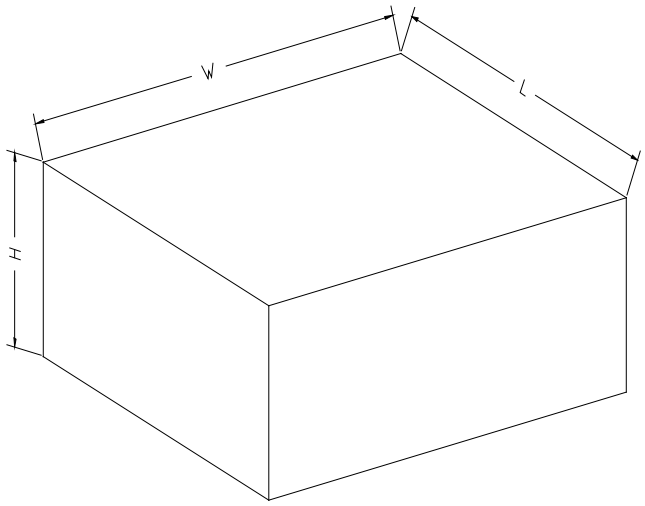
NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF TAPE AND REEL

Package Type	Reel Diameter	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
TSSOP-16	13"	12.4	6.80	5.40	1.50	4.0	8.0	2.0	12.0	Q1
TQFN-2.5×3.5-16L	13"	12.4	2.80	3.80	1.13	4.0	4.0	2.0	12.0	Q1

DD0001

CARTON BOX DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF CARTON BOX

Reel Type	Length (mm)	Width (mm)	Height (mm)	Pizza/Carton
13″	386	280	370	5

DD0002